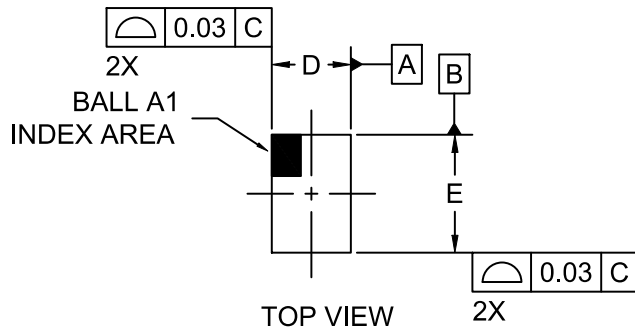


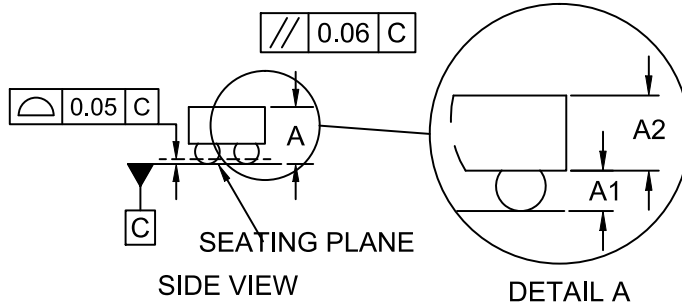
WLCSP6, 0.94x1.50x0.581
CASE 567WU
ISSUE O

DATE 17 JUL 2018

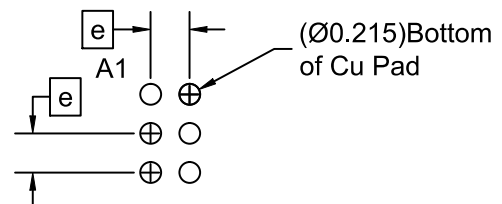
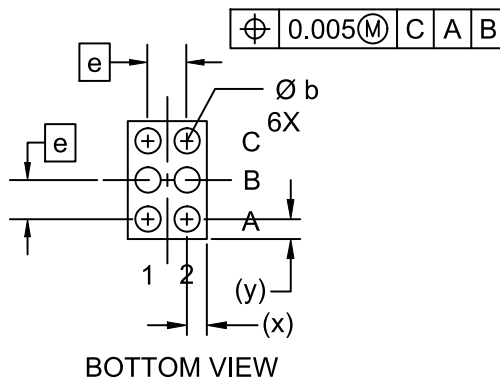


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.543	0.581	0.619
A1	0.185	0.203	0.221
A2	0.358	0.378	0.398
b	0.240	0.260	0.280
D	0.910	0.940	0.970
E	1.470	1.500	1.530
e	0.40 BSC		
x	0.255	0.270	0.285
y	0.335	0.350	0.365



**RECOMMENDED
MOUNTING FOOTPRINT
(NSMD PAD TYPE)**

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DESCRIPTION:	WLCSP6, 0.94x1.50x0.581	PAGE 1 OF 1

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